Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra-High-Speed U-MOSⅢ)

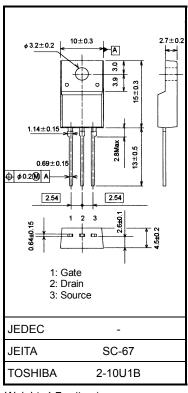
# **TK60A08J1**

### **Switching Regulator Application**

- High-Speed switching
- Small gate charge: Qg = 86nC (typ.)
- Low drain-source ON resistance: RDS (ON) =  $6.2 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 120S$
- Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 75 \text{ V)}$
- Enhancement-mode:  $V_{th} = 1.1 \sim 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

## Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			$V_{DSS}$	75	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )			$V_{DGR}$	75	V	
Gate-source voltage			V <sub>GSS</sub>	±20	V	
Drain current	DC	(Note 1)	I <sub>D</sub>	60	А	
	Pulse	(Note 1)	I <sub>DP</sub>	240		
Drain power dissipation (Tc = 25°C)			P <sub>D</sub>	45	W	
Single pulse avalanche energy (Note 2)			EAS	498	mJ	
Avalanche current			I <sub>AR</sub>	60	Α	
Repetitive avalanche energy (Note 3)			E <sub>AR</sub>	2.9	mJ	
Channel temperature			T <sub>ch</sub>	150	°C	
Storage temperature range			T <sub>stg</sub>	-55~150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Internal Connection



Note 1: Ensure that the channel & lead temperature does not exceed 150°C.

Note 2:  $V_{DD} = 25$  V,  $T_{ch} = 25$  °C, L = 200  $\mu H$ ,  $I_{AR} = 60$  A,  $R_G = 1$   $\Omega$ 

Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Handle with care.

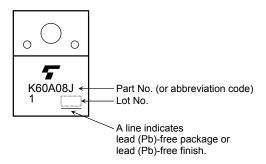
# **Electrical Characteristics (Ta = 25°C)**

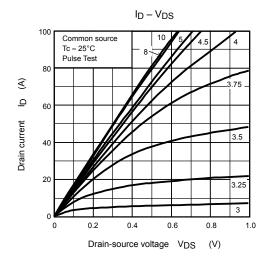
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	rain cut-OFF current		V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V	_	_	10	μΑ
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	75	_		V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	60	_	_	
Gate threshold voltage		V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.1	_	2.3	٧
Drain-source ON resistance		R <sub>DS</sub> (ON)	$V_{GS} = 4.5 \text{ V}, I_D = 30A$	_	7.1	9.3	- mΩ
			$V_{GS} = 10 \text{ V}, I_D = 30 \text{A}$	_	6.2	7.8	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 30 \text{ A}$	60	120	_	S
Input capacitance		C <sub>iss</sub>		_	5450	-	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10V, V_{GS} = 0 V, f = 1 MHz$		320		pF
Output capacitance		Coss			1260		
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $0 \text{ V}$ $V_{GS}$ $0 \text{ V}$ $V_{DD} \approx 30 \text{ A}$ $V_{DD} \approx 30 \text{ V}$ $V_{DD} \approx 30 \text{ V}$ $V_{DD} \approx 30 \text{ V}$	_	5	—	ns
	Turn-ON time	t <sub>on</sub>		—	20	_	
	Fall time	t <sub>f</sub>		_	15		
	Turn-OFF time	t <sub>off</sub>		_	96	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 60 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 60 \text{A}$	_	48		
			$V_{DD} \simeq 60 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{A}$		86	_	
Gate-source charge 1		Q <sub>gs1</sub>		_	16	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	$V_{DD} \simeq 60 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{A}$		20	_	
Gate switch charge		$Q_{\text{SW}}$			27		

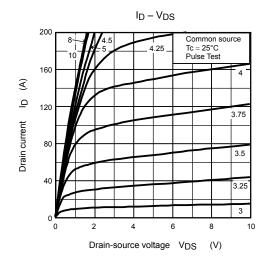
# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

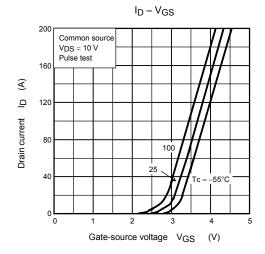
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	_	_	_	60	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	1	1	240	Α
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V}$		-0.9	-1.2	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 60 \text{ A}, V_{GS} = 0 \text{ V},$	_	63	_	ns
Reverse recovery charge	Qrr	$dI_{DR}/dt = 50 \text{ A}/\mu\text{s}$	_	63	_	nC

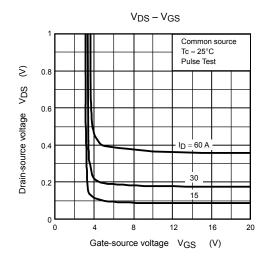
# Marking

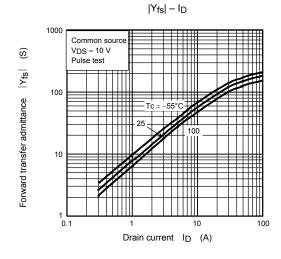


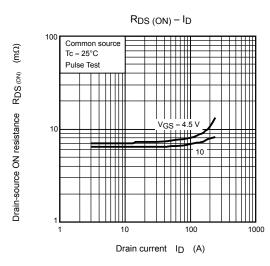




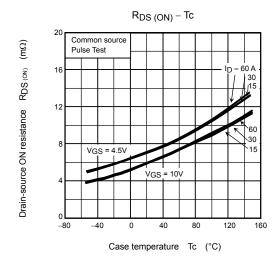


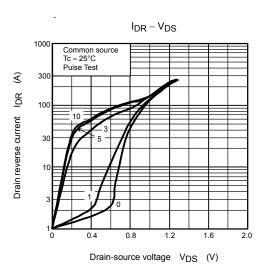


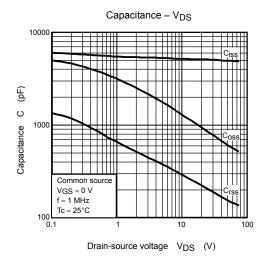


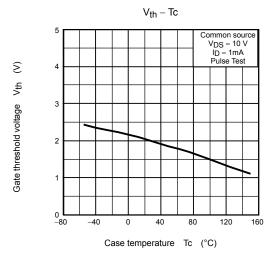


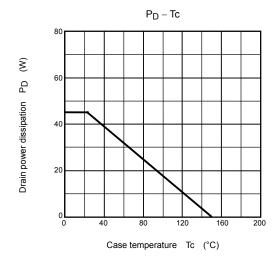
3 2007-02-05

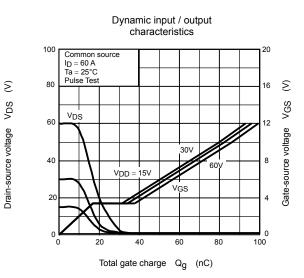




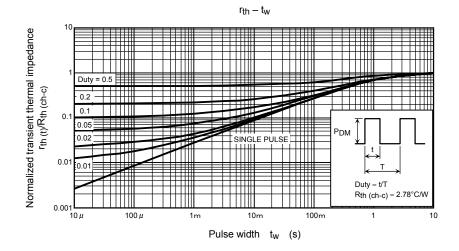


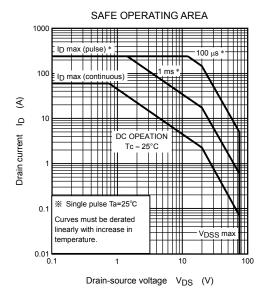


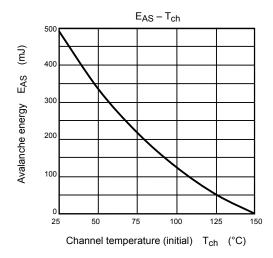


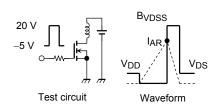


4 2007-02-05









$$\begin{aligned} R_G &= 1~\Omega \\ V_{DD} &= 25~V,~L = 200~\mu H \end{aligned} \qquad \text{EAS}$$

$$\mathsf{EAS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left( \frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

5 2007-02-05

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